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ABSTRACT

The invention relates to millimetric packaged electronic components for applications at high frequencies greater than 45 GHz. According to the invention, to facilitate the design of a system including MMIC chips working at these frequencies, it is proposed to use packages containing one or more chips, these packages making it possible to work at these frequencies and including two types of port: a port with transition by contactless electromagnetic coupling providing a connection with an antenna at the high working frequency F via a waveguide; and a port with microstrip or coaxial line type transition enabling a connection at a subharmonic frequency F/N (preferably $N = 6$ or 4 or, if necessary, 3) of the working frequency.

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